ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES	burn, Illinois, All	l rights reserved untions.	der both lev	is docume vel parts, tl	ent is a declaration en declaration	on of the substance	nces within the manufactu lower level materials for w	rer listed it which the m	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
IPC Web Site for Information or http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Ty   http://www.ipc.org/IPC-175x Distribut				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on		
Supplier Information												
mpany name* Company unique ID				Unique ID Authority			Response Date*					
onsemi									2023-06-08			
Contact Name	Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	et-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Ite	m Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
NCV7:	CV7513BFTR2G HEX LOW-SIDE		PRE-DRIVER		2023-06-08 PH1		PH1	1	75.1	mg	Each	
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Terminal Base Alloy		STD-020 MSL R	ating	Peak Proce	ss Body Tempe	s Body Temperature Max Time at Peak		Temperature Number of Reflow Cycles		les	
Matte Tin (Sn) - annealed CU Alloy 2					260	C	30	secon	ds 3			
Comments												
ATTENTION: MSL 2 Rated item requires Dry Pack	(after electrical t	test)										
for more information regarding material compositio	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.33	mg	Supplier	Silicon (Si)	7440-21-3		0.33	mg
Die Attach 3.19	3.19	mg	Supplier	Silver (Ag)	7440-22-4		2.3925	mg
			Supplier	Epoxy resins	129915-35-1		0.7975	mg
Lead Frame 49.99	49.99	mg	Supplier	Silver (Ag)	7440-22-4		0.15	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.05	mg
			Supplier	Silicon (Si)	7440-21-3		0.3499	mg
			В	Nickel (Ni)	7440-02-0		1.4997	mg
			Supplier	Copper (Cu)	7440-50-8		47.9404	mg
Mold Compound-Black	114.24	mg		Epoxy Phenol Resin	proprietary data		11.9952	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		102.2448	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	0.65	mg	Supplier	Gold (Au)	7440-57-5		0.65	mg